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Renesas Electronics website: http://www.renesas.com

April 1<sup>st</sup>, 2010 Renesas Electronics Corporation

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# MOS FIELD EFFECT TRANSISTOR $\mu$ PA1952

# P-CHANNEL MOS FIELD EFFECT TRANSISTOR FOR SWITCHING

#### **DESCRIPTION**

The  $\mu$  PA1952 is a switching device, which can be driven directly by a 1.8 V power source.

The device features a low on-state resistance and excellent switching characteristics, and is suitable for applications such as power switch of portable machine and so on.

#### **FEATURES**

- 1.8 V drive available
- Low on-state resistance

RDS(on)1 = 135 m $\Omega$  MAX. (VGS = -4.5V, ID = -1.0 A)

 $R_{DS(on)2} = 183 \text{ m}\Omega \text{ MAX.} (V_{GS} = -2.5 \text{ V}, I_{D} = -1.0 \text{ A})$ 

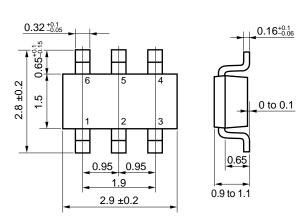
RDS(on)3 = 284 m $\Omega$  MAX. (VGS = -1.8 V, ID = -0.5 A)

#### ORDERING INFORMATION

PART NUMBER	PACKAGE
μ PA1952TE	SC-95 (Mini Mold Thin Type)

Marking: TP

#### PACKAGE DRAWING (Unit: mm)

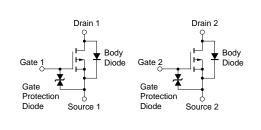


6: Drain 1 1: Gate 1 5: Source 1 4: Drain 2 3: Gate 2 2: Source 2

#### ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (Vgs = 0 V)	VDSS	-20	V
Gate to Source Voltage (Vps = 0 V)	Vgss	∓8.0	٧
Drain Current (DC)	ID(DC)	∓2.0	Α
Drain Current (pulse) Note1	I <sub>D(pulse)</sub>	∓8.0	Α
Total Power Dissipation (2 units) Note2	P <sub>T1</sub>	1.15	W
Total Power Dissipation (1 unit) Note2	P <sub>T2</sub>	0.57	W
Channel Temperature	$T_ch$	150	°C
Storage Temperature	$T_{stg}$	-55 to +150	°C

#### **EQUIVALENT CIRCUITS**



**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

2. Mounted on FR-4 board of 5000 mm<sup>2</sup> x 1.1 mm,  $t \le 5$  sec.

**Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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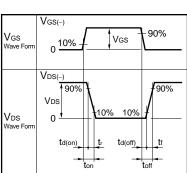


#### **ELECTRICAL CHARACTERISTICS (TA = 25°C)**

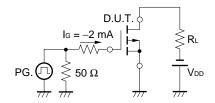
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = -20 V, V <sub>GS</sub> = 0 V			-10	μΑ
Gate Leakage Current	Igss	$V_{GS} = \mp 8.0 \text{ V}, V_{DS} = 0 \text{ V}$			∓10	μΑ
Gate Cut-off Voltage	V <sub>GS(off)</sub>	$V_{DS} = -10 \text{ V}, I_{D} = -1.0 \text{ mA}$	-0.45	-0.75	-1.5	V
Forward Transfer Admittance	<b>y</b> fs	$V_{DS} = -10 \text{ V}, I_{D} = -1.0 \text{ A}$	1.0	4.1		S
Drain to Source On-state Resistance	RDS(on)1	$V_{GS} = -4.5 \text{ V}, I_{D} = -1.0 \text{ A}$		108	135	mΩ
	RDS(on)2	$V_{GS} = -2.5 \text{ V}, I_{D} = -1.0 \text{ A}$		137	183	mΩ
	RDS(on)3	$V_{GS} = -1.8 \text{ V}, I_{D} = -0.5 \text{ A}$		170	284	mΩ
Input Capacitance	Ciss	V <sub>DS</sub> = -10 V		272		pF
Output Capacitance	Coss	V <sub>GS</sub> = 0 V		60		pF
Reverse Transfer Capacitance	Crss	f = 1.0 MHz		30		pF
Turn-on Delay Time	td(on)	$V_{DD} = -10 \text{ V}, I_{D} = -1.0 \text{ A}$		29		ns
Rise Time	tr	V <sub>GS</sub> = -4.0 V		120		ns
Turn-off Delay Time	td(off)	$R_G = 10 \Omega$		145		ns
Fall Time	<b>t</b> f			148		ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DD</sub> = -16 V		2.3		nC
Gate to Source Charge	Qgs	V <sub>GS</sub> = -4.0 V		0.6		nC
Gate to Drain Charge	Q <sub>GD</sub>	I <sub>D</sub> = -2.0 A		0.6		nC
Body Diode Forward Voltage	V <sub>F(S-D)</sub>	IF = 2.0 A, Vgs = 0 V		0.9		٧

#### **TEST CIRCUIT 1 SWITCHING TIME**

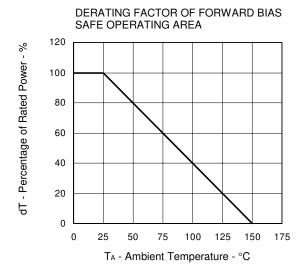
# PG. $\bigcap$ $V_{GS(-)}$ $\tau = 1 \mu s$ Duty Cycle $\leq 1\%$



#### **TEST CIRCUIT 2 GATE CHARGE**



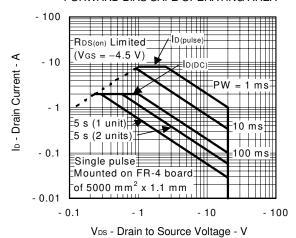
#### TYPICAL CHARACTERISTICS (TA = 25°C)



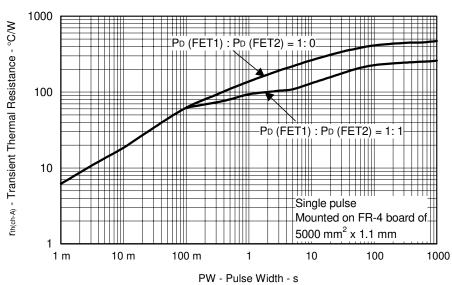
#### TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE 1.2 Mounted on FR-4 board of P<sub>T</sub> - Total Power Dissipation - W $5000 \text{ mm}^2 \text{ x } 1.1 \text{ mm}, \text{ t} \le 5 \text{ sec}.$ 0.8 2 units 0.6 unit-0.4 0.2 0 0 25 50 75 100 125 150 175

TA - Ambient Temperature - °C

#### FORWARD BIAS SAFE OPERATING AREA



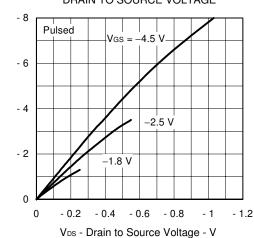
#### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



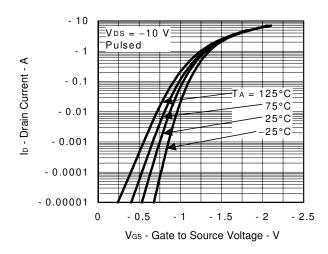
3

lo - Drain Current - A

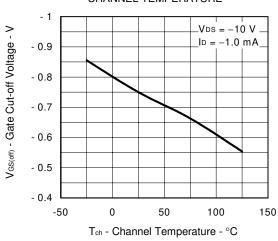
# DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



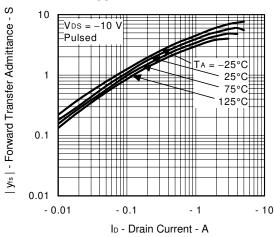
#### FORWARD TRANSFER CHARACTERISTICS



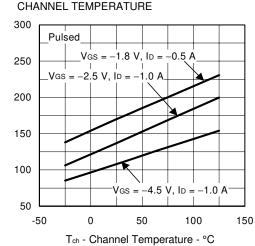
# GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



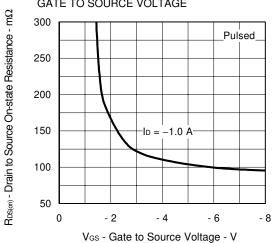
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



## DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

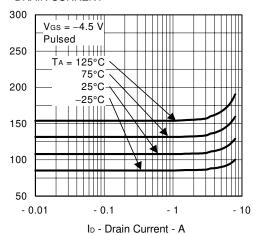


R<sub>DS(m)</sub> - Drain to Source On-state Resistance - mΩ

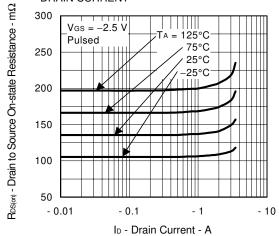
RDS(on) - Drain to Source On-state Resistance - mΩ

R<sub>DS(o1)</sub> - Drain to Source On-state Resistance - mΩ

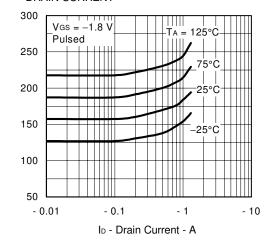
## DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



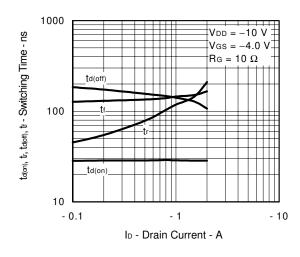
# DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



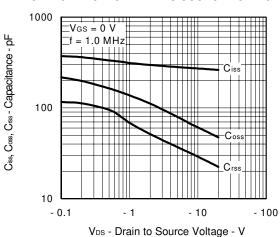
# DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



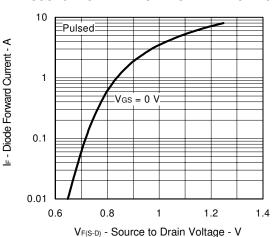
#### SWITCHING CHARACTERISTICS



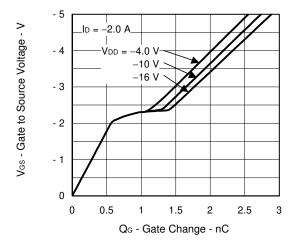
#### CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



#### SOURCE TO DRAIN DIODE FORWARD VOLTAGE



#### DYNAMIC INPUT/OUTPUT CHARACTERISTICS



NEC  $\mu$  PA1952

[MEMO]

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